SLLS121D - AUGUST 1990 - REVISED APRIL 1998

٠	Meets or Exceeds ANSI Standards EIA/TIA-422-B and RS-485 and ITU	N PACKAGE (TOP VIEW)	
•	Recommendation V.11 High-Speed Advanced Low-Power Schottky Circuitry	1A [1 16] V _{CC} 1Y [2 15] 4A 1Z [3 14] 4Y	
•	Designed for 20-MBaud Operation in Both Serial and Parallel Applications	G [] 4 13 [] 4Z 2Z [] 5 12 [] G	
•	Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments	2Y [] 6 11 [] 3Z 2A [] 7 10 [] 3Y	
•	Low Supply-Current Requirements: 55 mA Max	GND [8 9] 3A	
•	Wide Positive and Negative Input/Output Bus-Voltage Ranges	DW PACKAGE (TOP VIEW)	
٠	Driver Output Capacity \pm 60 mA		
٠	Thermal Shutdown Protection		
٠	Driver Positive and Negative Current	1Y [] 2 19 [] 4A NC [] 3 18 [] 4Y	
•	Limiting Logically Interchangeable With SN75172	1Z [] 4 17]] NC G [] 5 16 [] 4Z	
lesc	cription	2Z 🛛 6 15 🗋 🖸	
	•	NC [7 14] 3Z	
	The SN75ALS172A comprises four line drivers	2Y [] 8 13 [] NC	
	with 3-state differential outputs. They are designed to meet the requirements of ANSI Standards EIA/TIA-422-B and RS-485 and ITU	2A 9 12 3Y GND 10 11 3A	

NC - No internal connection

de

Recommendation V.11. This device is optimized for balanced multipoint bus transmission at rates of up to 20 Mbaud. Each driver features wide positive and negative common-mode output voltage ranges, making it suitable for party-line applications in noisy environments.

The SN75ALS172A provides positive- and negative-current limiting and thermal shutdown for protection from line-fault conditions on the transmission bus line. Shutdown occurs at a junction temperature of approximately 150°C.

The SN75ALS172A is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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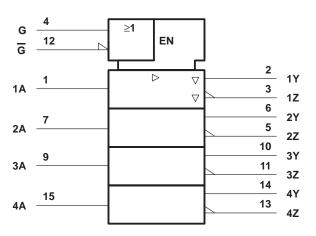
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FUNCTION TABLE (each driver)											
INPUT	ENA	BLES	OUTI	PUTS							
A	G	G	Y	Z							
Н	Н	Х	Н	L							
L	н	Х	L	н							
н	Х	L	н	L							
L	Х	L	L	н							
Х	L	Н	Z	Z							

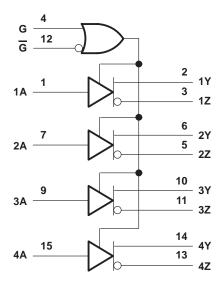
H = high level, L = low level, X = irrelevant, Z = high impedance (off)

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the N package.

logic diagram (positive logic)

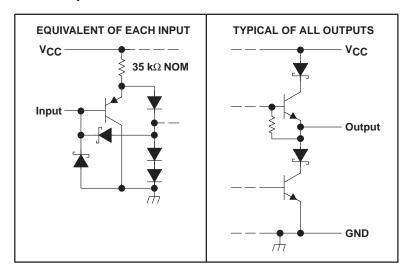


Pin numbers shown are for the N package.



SLLS121D - AUGUST 1990 - REVISED APRIL 1998

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1)	
Input voltage, V _I	
Output voltage range, VO	
Continuous total dissipation	
Storage temperature range, T _{stg} Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

 Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
 NOTE 1: All voltage values are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING								
DW	1125 mW	9 mW/°C	720 mW	585 mW								
Ν	1150 mW	9.2 mW/°C	736 mW	598 mW								

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.75	5	5.25	V
High-level input voltage, V _{IH}	2			V
Low-level input voltage, VIL			0.8	V
Common-mode output voltage, V _{OC}			12 –7	V
High-level output current, IOH			-60	mA
Low-level output current, IOL			60	mA
Operating free-air temperature, T _A	0		70	°C



SLLS121D - AUGUST 1990 - REVISED APRIL 1998

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN	түр†	MAX	UNIT	
VIK	Input clamp voltage	II = -18 mA				-1.5	V	
VO	Output voltage	IO = 0		0		6	V	
VOD1	Differential output voltage	I _O = 0		1.5		6	V	
Wonal	Differential output voltage	V _{CC} = 5 V,	$R_L = 100 \Omega$, See Figure 1	1/2 V _{OD1} 0	r 2‡		V	
VOD2		R _L = 54 Ω,	See Figure 1	1.5	2.5	5	V	
IVOD3	Differential output voltage	See Note 2		1.5		5	V	
$\Delta V_{OD} $	Change in magnitude of differential output voltage§	$R_L = 54 \Omega$ or 100 Ω,	See Figure 1			±0.2	V	
Voc	Common-mode output voltage \P	$R_L = 54 \Omega$ or 100 Ω,	See Figure 1			3 –1	V	
$\Delta V_{OC} $	Change in magnitude of common-mode output voltage§	$R_L = 54 \Omega$ or 100 Ω,	See Figure 1			±0.2	V	
IO	Output current with power off	$V_{CC} = 0,$	$V_{O} = -7 V$ to 12 V			±100	μΑ	
I _{OZ}	High-impedance-state output current	$V_{O} = -7$ V to 12 V				±100	μΑ	
Ιн	High-level input current	V _I = 2.7 V				20	μA	
۱ _{IL}	Low-level input current	V _I = 0.4 V				-100	μΑ	
los	Short-circuit output current	$V_{O} = -7 V$ to 12 V				±250	mA	
100	Supply surrent (all drivers)	Nalaad	Outputs enabled		36	55	A	
ICC	Supply current (all drivers)	No load Outputs disabled			15	30	mA	

[†] All typical values are at $V_{CC} = 5$ V and $T_A = 25^{\circ}C$.

[‡]The minimum V_{OD2} with a 100- Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.

§ Δ|V_{OD}| and Δ|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.

In ANSI Standard EIA/TIA-422-B, V_{OC}, which is the average of the two output voltages with respect to ground, is called output offset voltage, V_{OS}.

NOTE 2: See EIA Standard RS-485, Figure 3-5, Test Termination Measurement 2.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$

	PARAMETER	TEST CO	ONDITIONS	MIN	TYP†	MAX	UNIT
^t d(OD)	Differential-output delay time	R _L = 54 Ω,	See Figure 2	9	15	22	ns
^t PZH	Output enable time to high level	R _L = 110 Ω,	See Figure 3	30	45	70	ns
^t PZL	Output enable time to low level	R _L = 110 Ω,	See Figure 4	25	40	65	ns
^t PHZ	Output disable time from high level	R _L = 110 Ω,	See Figure 3	10	20	35	ns
^t PLZ	Output disable time from low level	R _L = 110 Ω,	See Figure 4	10	30	45	ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.



SLLS121D - AUGUST 1990 - REVISED APRIL 1998

PARAMETER MEASUREMENT INFORMATION

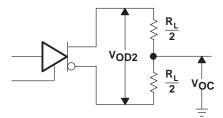
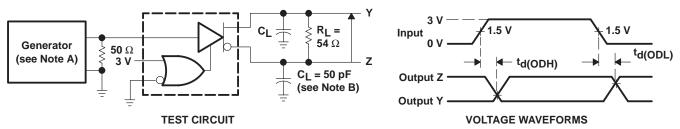
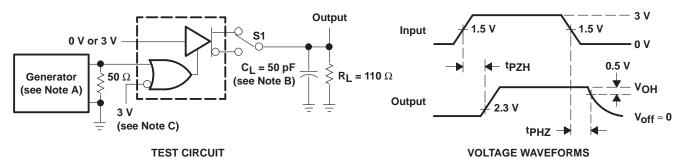


Figure 1. Differential and Common-Mode Output Voltages



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, $Z_0 = 50 \Omega$, duty cycle = 50%, $t_f \le 5$ ns, $t_r \le 5$ ns.
 - B. $\ \ C_L$ includes probe and stray capacitance.

Figure 2. Differential Output Test Circuit and Voltage Waveforms

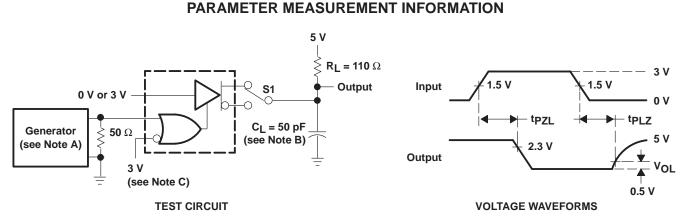


- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, $Z_0 = 50 \Omega$, duty cycle = 50%, $t_f \le 5$ ns, $t_r \le 5$ ns.
 - B. CL includes probe and stray capacitance.
 - C. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 3. Test Circuit and Voltage Waveforms, tPZH and tPHZ



SLLS121D - AUGUST 1990 - REVISED APRIL 1998



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, $Z_0 = 50 \Omega$, duty cycle = 50%, $t_f \le 5$ ns, $t_r \le 5$ ns.
 - B. C_L includes probe and stray <u>capacitance</u>.
 - C. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 4. Test Circuit and Voltage Waveforms, tpz1 and tp17





PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	•	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
SN75ALS172ADW	LIFEBUY	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS172A	
SN75ALS172ADWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS172A	Samples
SN75ALS172AN	LIFEBUY	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75ALS172AN	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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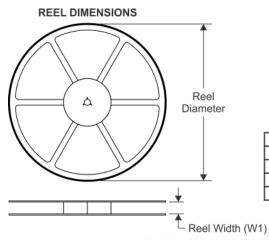
PACKAGE OPTION ADDENDUM

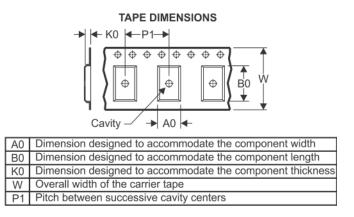
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



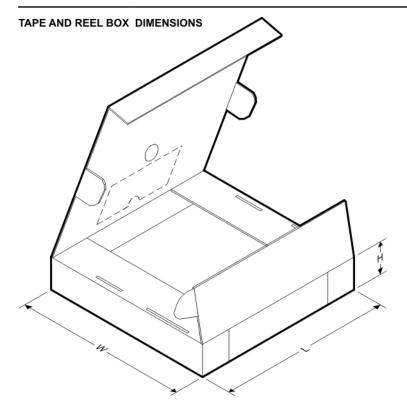
*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS172ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1



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PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN75ALS172ADWR	SOIC	DW	20	2000	367.0	367.0	45.0	



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN75ALS172ADW	DW	SOIC	20	25	506.98	12.7	4826	6.6
SN75ALS172ADW	DW	SOIC	20	25	507	12.83	5080	6.6
SN75ALS172AN	N	PDIP	16	25	506	13.97	11230	4.32

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



DW0020A

EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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